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REMARKS

Claims 1-25 are currently pending in the subject application and are presently under consideration. The specifications have been amended to correct formalities. A clean version of all pending claims is found at pages 6-11. Claims 1, 12, 17, and 23 have been amended herein.

Favorable reconsideration of the subject patent application is respectfully requested in view of the comments and amendments herein.

I. Rejection of Claims 1-25 Under 35 U.S.C. §102(b)

Claims 1-25 stand rejected under 35 U.S.C. §102(b) as being anticipated by Good *et al.* (US 4,943,827). It is respectfully submitted that this rejection should be withdrawn for at least the following reasons. Good *et al.* does not teach or suggest the claimed invention.

For a prior art reference to anticipate, 35 U.S.C. §102 requires that "each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference." *In re Robertson*, 169 F.3d 743, 745, 49 USPQ2d 1949, 1950 (Fed. Cir. 1999) (quoting *Verdegaal Bros., Inc. v. Union Oil Co.*, 814 F.2d 628, 631, 2USPQ2d 1051, 1053 (Fed. Cir. 1987)).

As recited by independent claims 1, 12, 17, and 23, the subject invention relates to a system and method for regulating semiconductor substrate (or mask and/or reticle) temperature. Applicants have amended claim 1 (and claims 12, 17, and 23 similarly) to now state, "an exposing source operative to expose a **semiconductor** substrate and at least one temperature sensor operative to proximally sense temperature characteristics of the **semiconductor** substrate, including during an exposure cycle." This amendment is made for purposes of clarity, and support for the amendment can be found, for example, at page 2, line 31 (... the present invention provides for a system to monitor temperature of a substrate, such as a mask, reticle, or wafer). Those skilled in the art will recognize that semiconductor is synonymous with wafer (which is recited in dependent claims 7 and 22), as evidenced by the use of the phrase "semiconductor wafer" in the background section of the present invention.

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Good *et al.* does not teach or suggest a *semiconductor substrate*. Rather, Good *et al.* discloses a substrate utilized in connection with visible image forming. In view of at least the above, it is readily apparent that Good *et al.* does not anticipate the subject invention as recited in independent claims 1, 12, 17, and 23 (and claims 2-11, 13-16, 18-22, and 24-25 which respectively depend there from). Withdrawal of this rejection is respectfully requested.

II. Rejection of Claims 1-25 Under 35 U.S.C. §102(b)

Claims 1-25 stand rejected under 35 U.S.C. §102(b) as being anticipated by Mori *et al.* (US 5,610,965). It is respectfully submitted that this rejection should be withdrawn for at least the following reasons. Mori *et al.* does not teach or suggest all of the limitations of the claimed invention.

As amended in independent claim 1 (and similarly in independent claims 12, 17, and 23), the subject invention comprises *a plurality of temperature sensors* operative to proximally sense temperature characteristics of the semiconductor substrate.

The subject invention contemplates utilizing *a plurality of temperature sensors* to provide the temperature of *one semiconductor substrate*. This aspect of the subject invention provides advantages over prior art by facilitating detection of temperature characteristics within zones of a semiconductor substrate, which provides more feedback concerning semiconductor substrate temperature and greater control over exposure. Furthermore, greater uniformity of exposure is facilitated employing the claimed invention. Mori *et al.* does not teach or suggest such a limitation. Rather, Mori *et al.* discloses employing one temperature sensor for one semiconductor substrate. For example, Mori *et al.* discloses utilizing "a temperature sensor 5 fixed on the mask stage 3 to detect the temperature of the mask (mask stage) [and] a temperature sensor 6 fixed on the wafer stage to detect the temperature of the wafer (wafer stage)."

In view of at least the above, it is readily apparent that Mori *et al.* does not anticipate the subject invention as recited in independent claims 1, 12, 17, and 23 (and claims 2-11, 13-16, 18-22, and 24-25 which respectively depend there from). Withdrawal of this rejection is respectfully requested.

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III. Conclusion

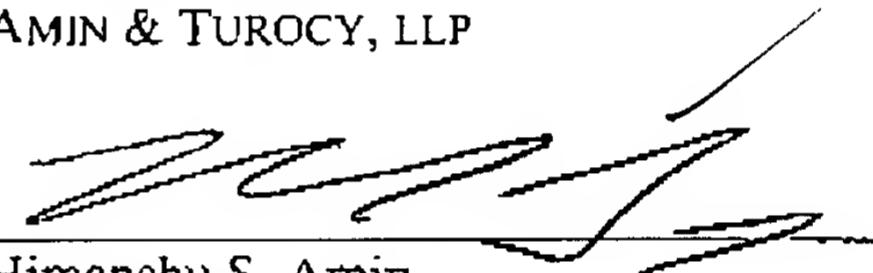
The present application is believed to be condition for allowance in view of the above amendments and comments. A prompt action to such end is earnestly solicited.

In the event any fees are due in connection with this document, the Commissioner is authorized to charge those fees to Deposit Account No. 50-1063.

Should the Examiner believe a telephone interview would be helpful to expedite favorable prosecution, the Examiner is invited to contact applicants' undersigned representative at the telephone number listed below.

Respectfully submitted,

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